IN THE CLAIMS:

Please amend the claims as follows.

1. (Currently Amended) A stock sheet for a multilayer flexible wiring board comprising:

a flexible sheet-like substrate configured to be transported in a predetermined direction, and

a plurality of wiring patterns directly arranged on a same side surface of the substrate in a direction perpendicular to the predetermined direction, wherein the plurality of wiring patterns correspond to individual layers of a multilayer flexible wiring board.

2. (Cancelled).

3. (Withdrawn) A mask for exposure used in a photoetching process, comprising a sheet-like mask body, and a plurality of pattern holes arranged in a predetermined direction in the mask body and corresponding to individual layers of wiring boards of a multilayer flexible wiring board.

4. (Withdrawn) The mask of claim 3 wherein each pattern hole is arranged in a direction perpendicular to a transporting direction of the mask body.

5. (Withdrawn) The mask of claim 3 wherein each of the pattern holes corresponds to a wiring pattern.

6. (Withdrawn) The mask of claim 4 wherein each of the pattern holes corresponds to a wiring pattern.

7. (Withdrawn) A method for manufacturing a multilayer flexible wiring board comprising: using a mask for exposure in which a plurality of pattern holes corresponding to individual layers of wiring boards of a multilayer flexible wiring board are arranged in a predetermined direction in a sheet-like mask body; and exposing the mask body to light while it is transported in a predetermined direction.

8. (Withdrawn) The process of claim 7 wherein each pattern is arranged in a direction perpendicular to a transporting direction of the mask body.

9. (Withdrawn) The process of claim 7 wherein each of the pattern holes corresponds to a wiring pattern.

10. (Withdrawn) The process of claim 8 wherein each of the pattern holes corresponds to a wiring pattern.